

Special Issue

Design, Analysis, Intelligent Control and Optimization of Industrial and Manufacturing Processes

Message from the Guest Editors

We aim to promote discussion among researchers and engineers and share the most recent advancements in this field. We encourage the submission of studies that cover aspects related to the industrial and manufacturing processes, including, but not limited to, the following topics:

- Smart manufacturing, design, analysis, intelligent control, and optimization of the processes;
- Special technologies in manufacturing, like additive manufacturing (3D printing);
- High-precision manufacturing optimized techniques, like surface milling, etching, electroforming and die casting;
- Techniques for improved manufacturing throughput;
- Industry 4.0 and its main technologies, such as the Internet of Things (IoT), cyber-physical systems (CPS), big data, simulation and digital twins, advanced robotics, augmented reality, artificial intelligence, machine learning, etc.;
- Trends in supply chain management and logistics;
- Advanced materials for industry, manufacturing, and products, like high-strength materials, lightweight materials, and carbon fiber;
- New or hybrid forms of manufacturing and manufacturing systems.

Guest Editors

Dr. Daynier Rolando Delgado Sobrino

Faculty of Materials Science and Technology in Trnava, Slovak
University of Technology in Bratislava, Bratislava, Slovakia

Dr. Rafał Gołębski

Faculty of Mechanical Engineering and Computer Science, Department
of Technology and Automation, Częstochowa University of Technology,
42-201 Częstochowa, Poland

Deadline for manuscript submissions

closed (20 July 2025)



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



mdpi.com/si/182179

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls@mdpi.com

[mdpi.com/journal/
appls](https://mdpi.com/journal/appls)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)